

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): An interposer configured to be located between a package substrate made of resin and an IC chip, the interposer comprising:

an insulating base material, wherein a Young's modulus of the insulation base material is 55 to 440GPa and a thickness of said insulation base material is 0.05 to 1.5 times the thickness of the package substrate; and

a plurality of through holes provided through the insulating base material, at ~~least one~~ each of said plurality of through holes having a diameter of 125  $\mu$ m or less and having formed therein a through hole conductor for connecting said package substrate with the IC chip,

wherein the plurality of through holes in the insulating base material are arranged in the form of a grid.

Claim 2 (Previously Presented): The interposer according to Claim 1, wherein the thickness of said insulation base material is at least 0.08 times the thickness of core of the package substrate.

Claim 3 (Previously Presented): The interposer according to Claim 1, wherein the size of said insulation base material is equal to or larger than a projection area of an electronic component loaded on the interposer, and equal to or less than a projection area of the package substrate.

Claim 4 (Canceled).

Claim 5 (Previously Presented): The interposer according to Claim 1, wherein said package substrate is a multilayer printed wiring board.

Claim 6 (Previously Presented): The interposer according to Claim 1, wherein said through hole conductor is made of metal plating.

Claim 7 (Previously Presented): The interposer according to Claim 1, wherein said through hole conductor is made of metallic paste.

Claim 8 (Previously Presented): The interposer according to Claim 1, wherein as regards the sectional shape of the through hole in the insulation base material, the diameter of an opening in at least an end face of the through hole is equal to or larger than the diameter of the hole in the center of the through hole.

Claim 9 (Previously Presented): A multilayer printed wiring board having the interposer according to Claim 1.

Claim 10 (Currently Amended): The interposer according to Claim 1, wherein a diameter of each of the plurality of through [[hole]] holes is from 30  $\mu\text{m}$  to 125  $\mu\text{m}$  ~~or less~~.

Claim 11 (Currently Amended): An interposer configured to be located between a package substrate made of resin and an IC chip, the interposer comprising:

an insulating base material, wherein a Young's modulus of the insulation base material is 55 to 440GPa and a thickness of said insulation base material is 0.05 to 1.5 times the thickness of the package substrate; and

a plurality of through holes provided through the insulating base material, at ~~least one~~ each of said plurality of through holes having a diameter of 125  $\mu$ m or less and having formed therein a through hole conductor for connecting said package substrate with the IC chip,

wherein the plurality of through holes in the insulating base material are arranged in the form of a staggered arrangement.

Claim 12 (Currently Amended): The interposer according to Claim 11, wherein [[the]] a thickness of said insulation base material is at least 0.08 times the thickness of core of the package substrate.

Claim 13 (Previously Presented): The interposer according to Claim 11, wherein the size of said insulation base material is equal to or larger than projection area of an electronic component loaded on the interposer, and equal to or less than a projection area of the package substrate.

Claim 14 (Previously Presented): The interposer according to Claim 11, wherein said package substrate is a multilayer printed wiring board.

Claim 15 (Previously Presented): The interposer according to Claim 11, wherein said through hole conductor is made of metal plating.

Claim 16 (Previously Presented): The interposer according to Claim 11, wherein said through hole conductor is made of metallic paste.

Claim 17 (Previously Presented): The interposer according to Claim 11, wherein as regards the sectional shape of the through hole in the insulation base material, the diameter of an opening in at least an end face of the through hole is equal to or larger than the diameter of the hole in the center of the through hole.

Claim 18 (Previously Presented): A multilayer printed wiring board having the interposer according to Claim 11.

Claim 19 (Currently Amended): The interposer according to Claim 11, wherein a diameter of each of the plurality of through [[hole]] holes is from 30  $\mu\text{m}$  to 125  $\mu\text{m}$  or less.

Claim 20 (Previously Presented): The interposer according to Claim 1, wherein a set of said plurality of through holes corresponding to either a power source electrode or ground electrode terminal of the IC chip are arranged in said grid.

Claim 21 (Previously Presented): The interposer according to Claim 20, wherein the plurality of through holes are arranged to effect substantially uniform temperature of the interposer.

Claim 22 (Previously Presented): The interposer according to Claim 1, wherein each of the plurality of through holes are arranged at substantially equal distance from each other.